Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

OptiMOS®-T2 Power-Transistor

AEC Qualified

RoHS

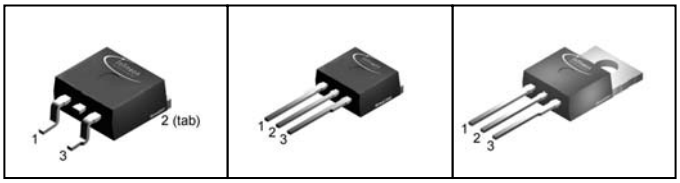
Product Summary

V_{DS}	30	V
$R_{DS(on),max}$ (SMD version)	14.6	mΩ
I_D	22	A

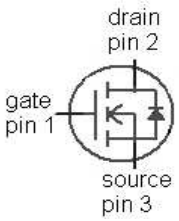
Features

- N-channel - Enhancement mode
- Automotive AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green product (RoHS compliant)
- Ultra low Rds(on)
- 100% Avalanche tested

PG-TO263-3-2 PG-TO262-3-1 PG-TO220-3-1



Type	Package	Marking
IPB22N03S4L-15	PG-TO263-3-2	4N03L15
IPI22N03S4L-15	PG-TO262-3-1	4N03L15
IPP22N03S4L-15	PG-TO220-3-1	4N03L15



Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current[1]	I_D	T_C=25 °C, V_{GS}=10 V	22	A
		T_C=100 °C, V_{GS}=10 V[2]	22	
Pulsed drain current[2]	$I_{D,pulse}$	T_C=25 °C	88	
Avalanche energy, single pulse	E_{AS}	I_D=22 A	20	mJ
Avalanche current, single pulse	I_{AS}	T_C=25 °C	22	A
Gate source voltage	V_{GS}		±16	V
Power dissipation	P_{tot}	T_C=25 °C	31	W
Operating and storage temperature	T_j, T_{stg}		-55 ... +175	°C
IEC climatic category; DIN IEC 68-1			55/175/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics[2]						
Thermal resistance, junction - case	R_{thJC}		-	-	4.9	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}		-	-	62	
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm^2 cooling area[3]	-	-	40	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D= 1 mA	30	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=10 µA	1.0	1.5	2.2	
Zero gate voltage drain current	I_{DSS}	V_{DS}=30 V, V_{GS}=0 V, T_j=25 °C	-	0.01	1	µA
		V_{DS}=30 V, V_{GS}=0 V, T_j=125 °C[2]	-	10	1000	
		V_{DS}=18 V, V_{GS}=0 V, T_j=85 °C[2]	-	5	60	
Gate-source leakage current	I_{GSS}	V_{GS}=16 V, V_{DS}=0 V	-	1	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=4.5 V, I_D=11 A	-	17.5	19.8	mΩ
		V_{GS}=4.5 V, I_D=11 A, SMD version	-	17.2	19.5	
		V_{GS}=10 V, I_D=22 A	-	12.7	14.9	
		V_{GS}=10 V, I_D=22 A, SMD version	-	12.4	14.6	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics[2]						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=25 V, f=1 MHz	-	750	980	pF
Output capacitance	C_{oss}		-	190	250	
Reverse transfer capacitance	C_{rss}		-	10	20	
Turn-on delay time	$t_{d(on)}$	V_{DD}=15 V, V_{GS}=10 V, I_D=22 A, R_G=3.5 Ω	-	3	-	ns
Rise time	t_r		-	2	-	
Turn-off delay time	$t_{d(off)}$		-	12	-	
Fall time	t_f		-	2	-	
Gate Charge Characteristics[2]						
Gate to source charge	Q_{gs}	V_{DD}=24 V, I_D=22 A, V_{GS}=0 to 10 V	-	2.2	3	nC
Gate to drain charge	Q_{gd}		-	1.4	3	
Gate charge total	Q_g		-	11	14	
Gate plateau voltage	$V_{plateau}$		-	3.4	-	V
Reverse Diode						
Diode continous forward current[2]	I_S	T_C=25 °C	-	-	22	A
Diode pulse current[2]	$I_{S,pulse}$		-	-	88	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=22 A, T_j=25 °C	0.6	0.95	1.3	V
Reverse recovery time[2]	t_{rr}	V_R=15 V, I_F=I_S, di_F/dt=100 A/µs	-	12	-	ns
Reverse recovery charge[2]	Q_{rr}		-	10	-	nC

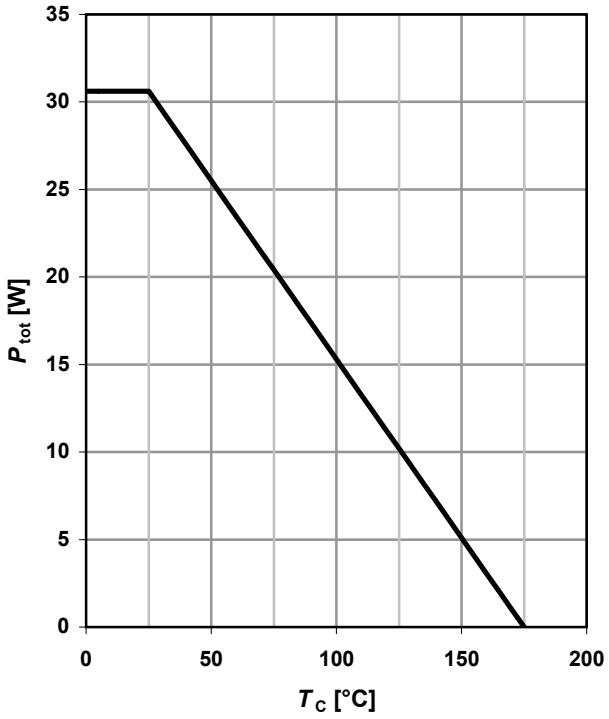
[1] Current is limited by bondwire; with an R_{thJC} = 4.9K/W the chip is able to carry 36A at 25°C. For detailed information see Application Note ANPS071E at *www.infineon.com/optimos*

[2] Defined by design. Not subject to production test.

[3] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

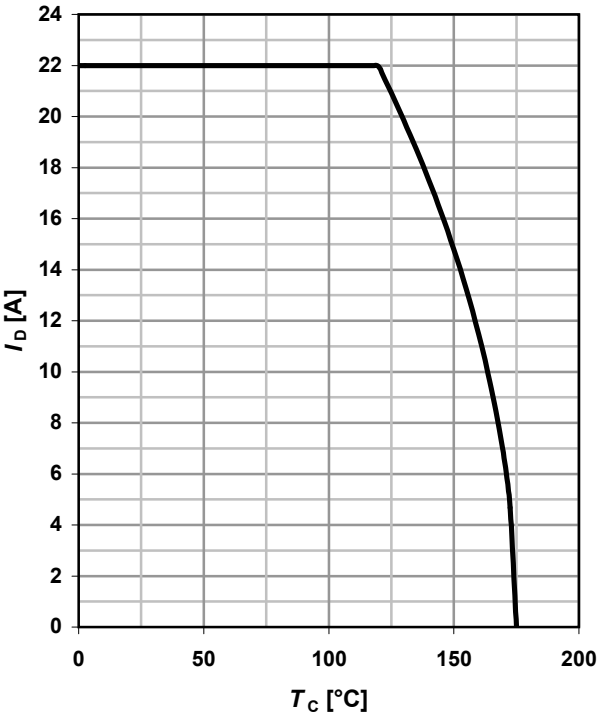
1 Power dissipation

$P_{tot} = f(T_C)$; $V_{GS} \geq 6$ V



2 Drain current

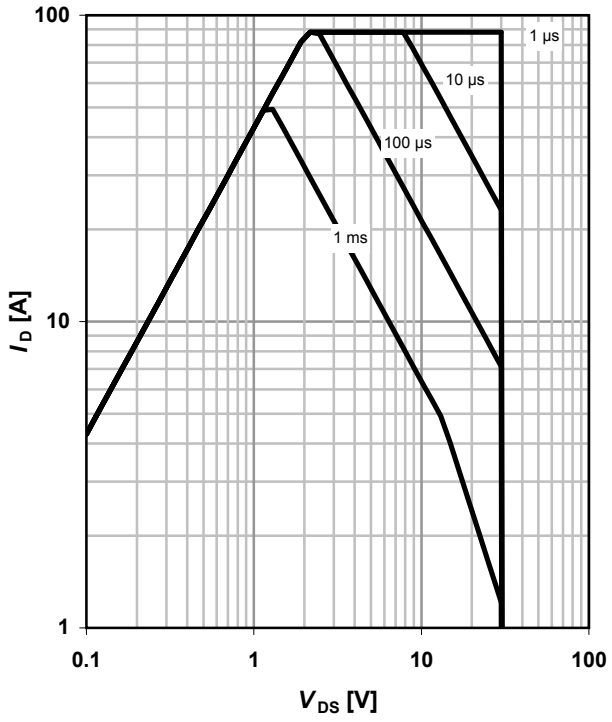
$I_D = f(T_C)$; $V_{GS} \geq 6$ V; SMD



3 Safe operating area

$I_D = f(V_{DS})$; $T_C = 25$ °C; $D = 0$, SMD

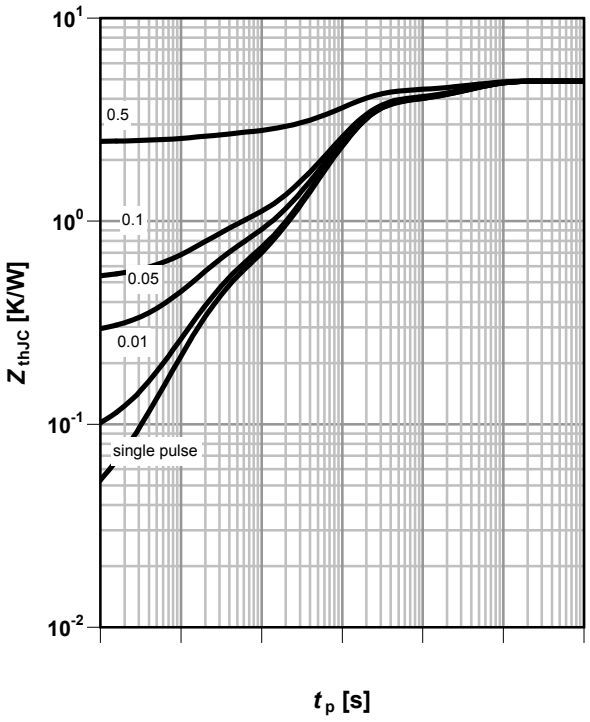
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

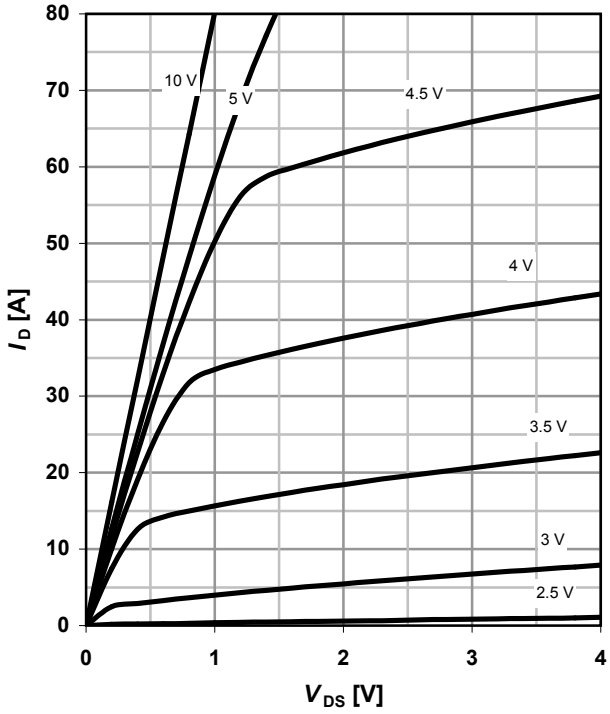
parameter: $D = t_p / T$



5 Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 25$ °C, SMD

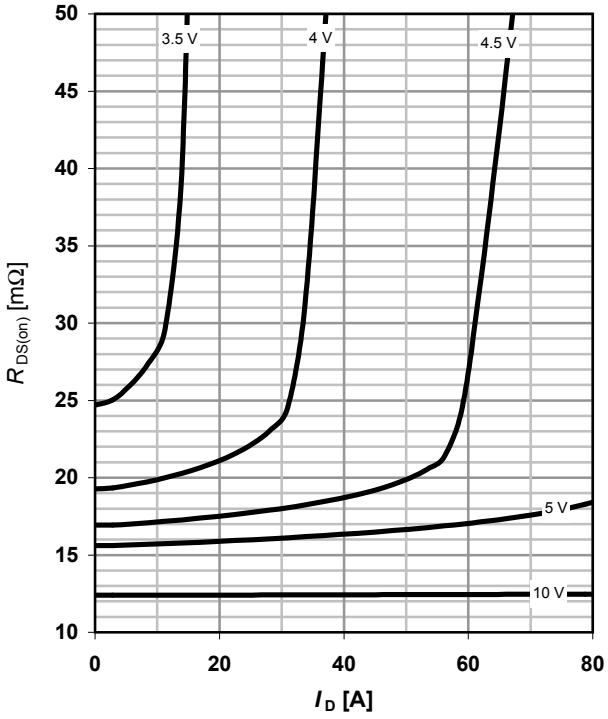
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = f(I_D)$; $T_j = 25$ °C, SMD

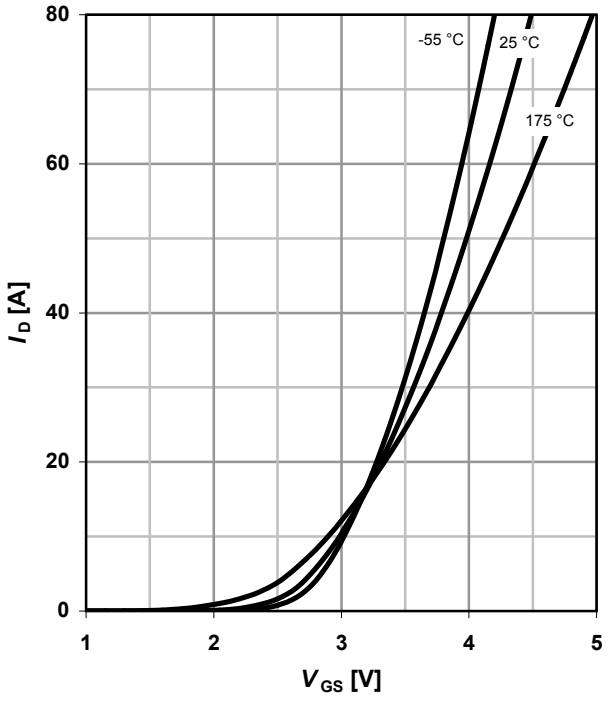
parameter: V_{GS}



7 Typ. transfer characteristics

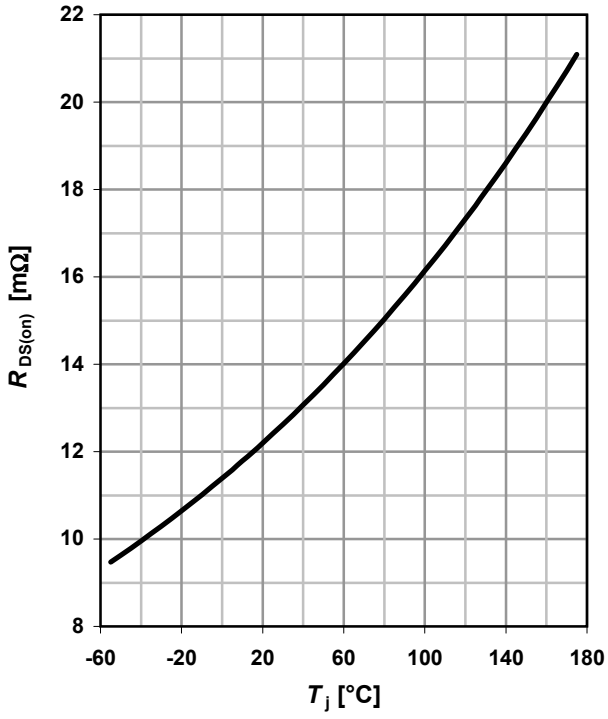
$I_D = f(V_{GS})$; $V_{DS} = 6$V

parameter: T_j



8 Typ. drain-source on-state resistance

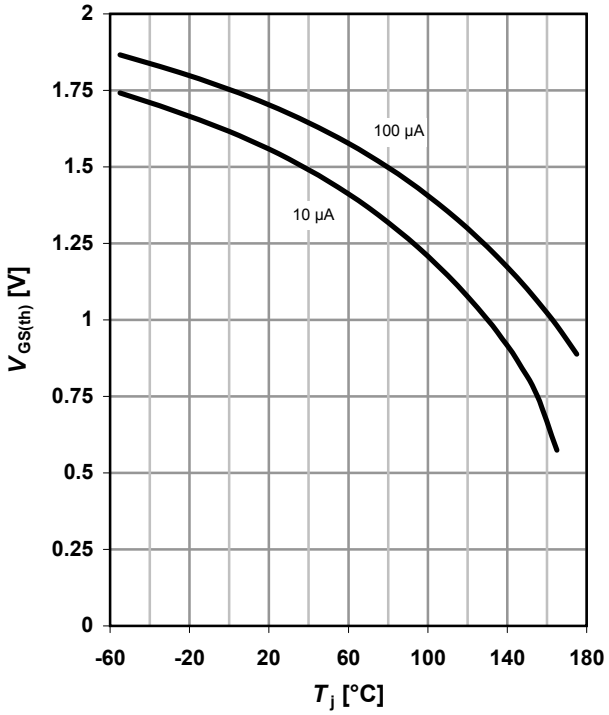
$R_{DS(on)} = f(T_j)$; $I_D = 22$ A; $V_{GS} = 10$ V, SMD



9 Typ. gate threshold voltage

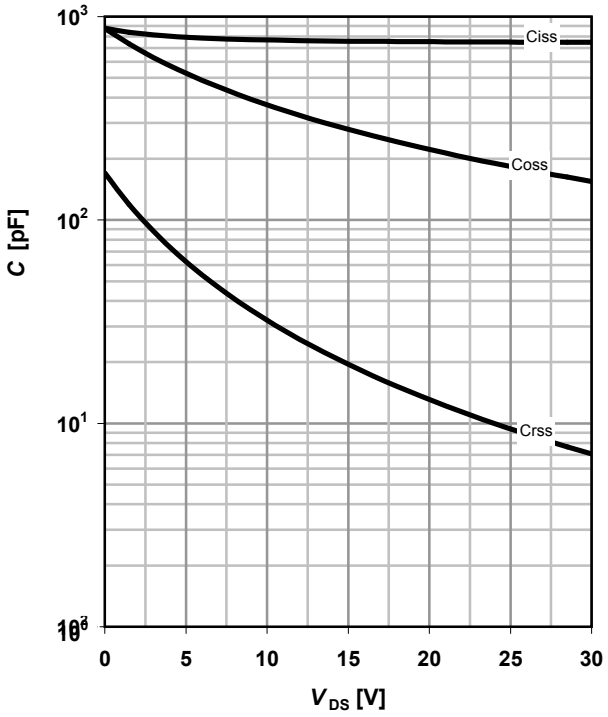
$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$

parameter: I_D



10 Typ. capacitances

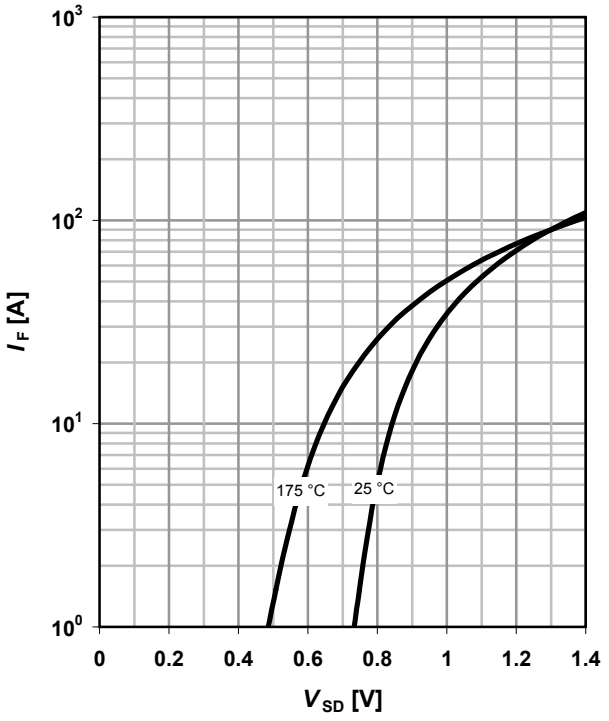
$C = f(V_{DS})$; $V_{GS} = 0$ V; $f = 1$ MHz



11 Typical forward diode characteristicis

IF = f(V_{SD})

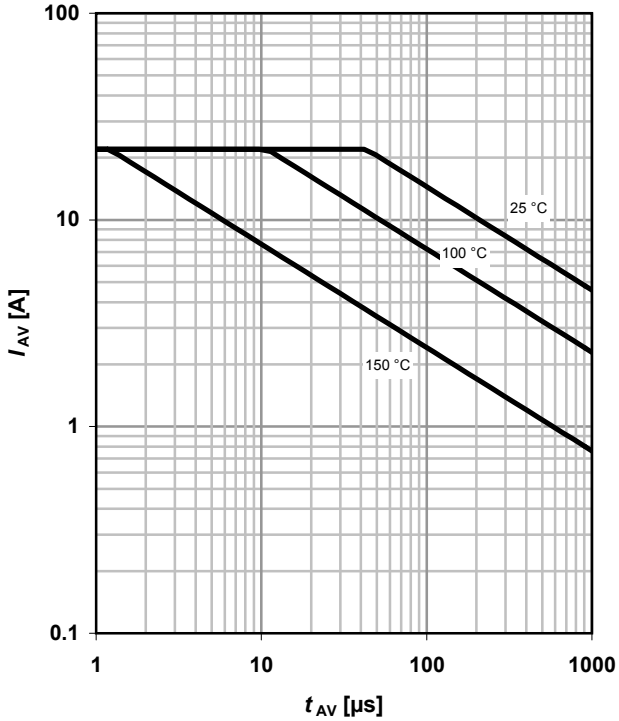
parameter: T_j



12 Typ. avalanche characteristics

$I_{AS} = f(t_{AV})$

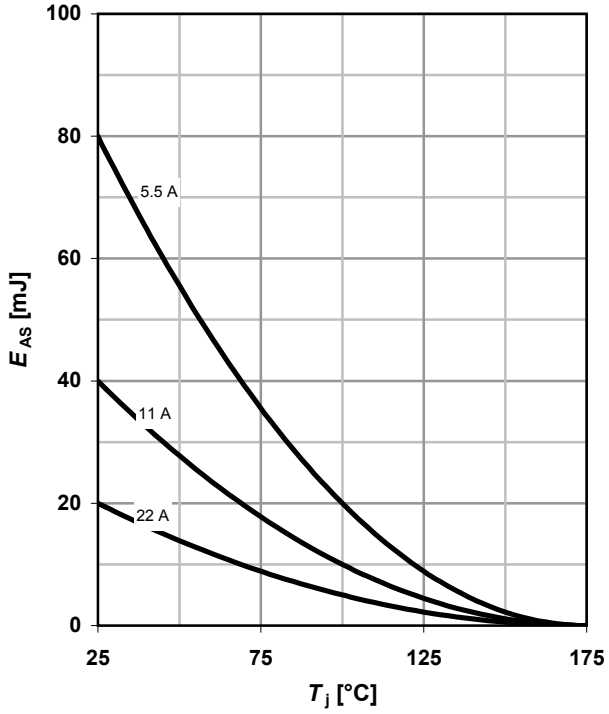
parameter: $T_{j(start)}$



13 Typical avalanche energy

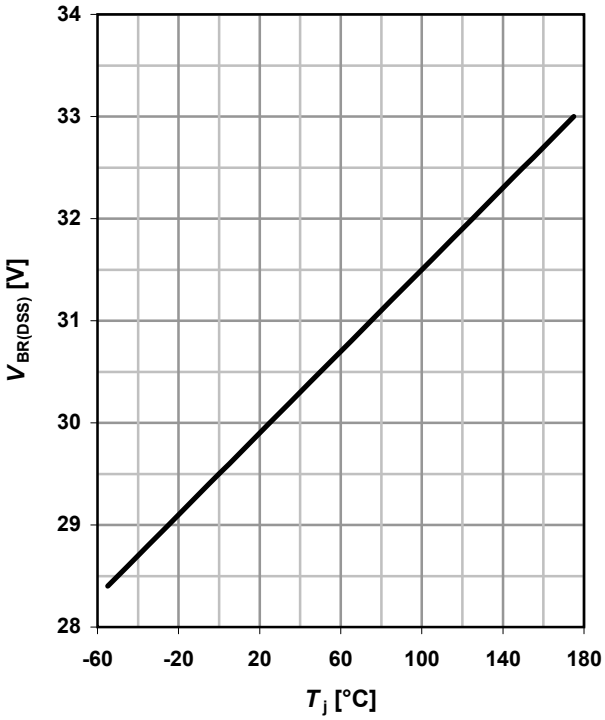
$E_{AS} = f(T_j)$

parameter: I_D



14 Typ. drain-source breakdown voltage

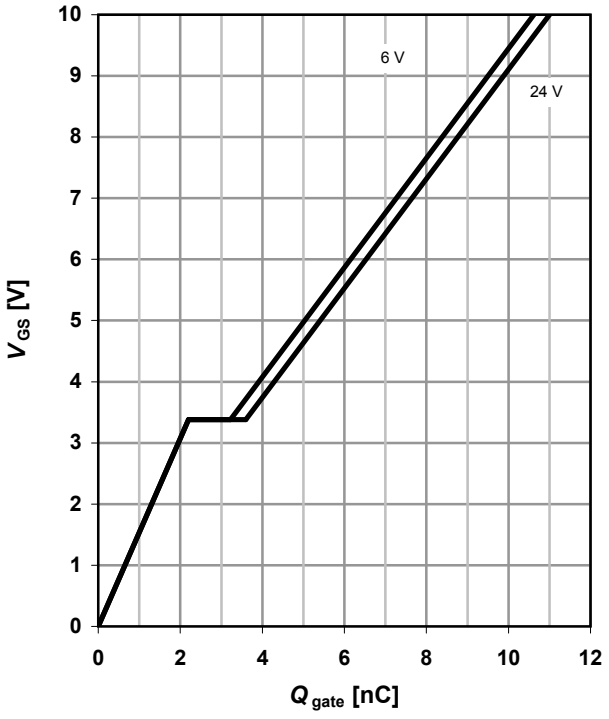
$V_{BR(DSS)} = f(T_j)$; $I_D = 1$ mA



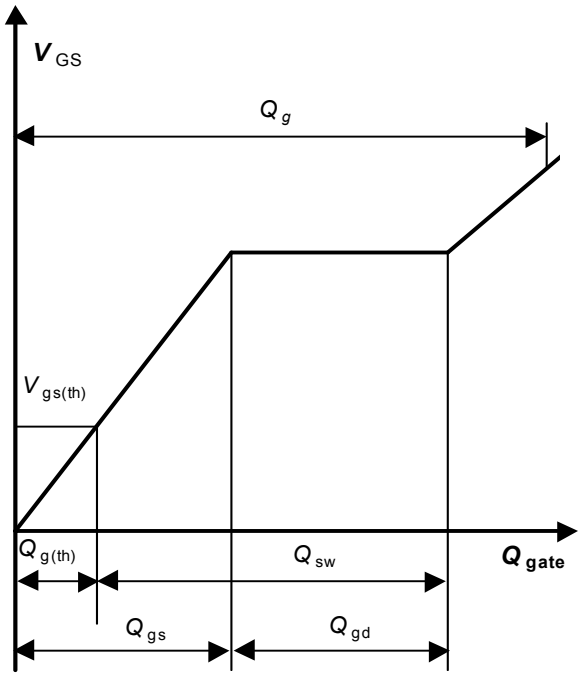
15 Typ. gate charge

$V_{GS} = f(Q_{gate})$; $I_D = 22$ A pulsed

parameter: V_{DD}



16 Gate charge waveforms



Published by
Infineon Technologies AG
81726 Munich, Germany

Legal Disclaimer
The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics (“Beschaffenheitsgarantie”). With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non‑infringement of intellectual property rights of any third party.

Information
For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (**www.infineon.com**).

Warnings
Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.
Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

Revision History

Version	Date	Changes